



GENERAL DESCRIPTION

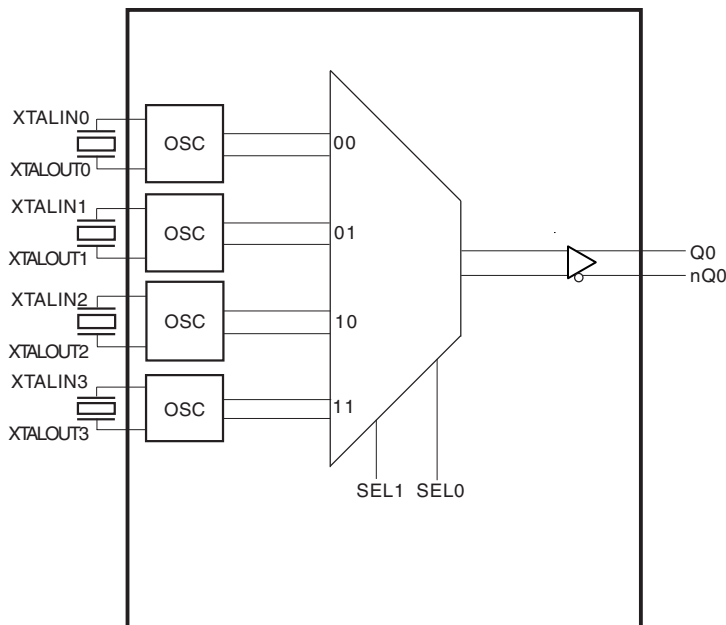


The ICS85357-11 is a 4:1 or 2:1, Crystal Oscillator-to-3.3V LVPECL / ECL Multiplexer and is a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS85357-11 has 4 selectable crystal inputs. The device can support 10MHz to 27MHz parallel resonant crystals by connecting external capacitors between XTALIN/XTALOUT and ground. The select pins have internal pulldown resistors and leaving one input unconnected (pulled to logic low by the internal resistor) will transform the device into a 2:1 multiplexer. The SEL1 lead is the most significant line and the binary number applied to the select pins will select the same numbered data input (i.e., 00 selects XTALIN0/XTALOUT0).

FEATURES

- 1 differential 3.3V LVPECL output
- 4:1 or 2:1 Crystal Oscillator Multiplexer
- Supports parallel resonant crystals with a frequency range of 10MHz to 27MHz. The oscillator circuit is optimized for parallel resonant mode, and will require external capacitance
- Maximum output frequency: 27MHz
- LVCMOS/LVTTL SEL0 and SEL1 inputs have internal pulldown resistors
- LVPECL mode operating voltage supply range: $V_{CC} = 3.135V$ to $3.465V$, $V_{EE} = 0V$
- ECL mode operating voltage supply range: $V_{CC} = 0V$, $V_{EE} = -3.135V$ to $-3.465V$
- 0°C to 70°C ambient operating temperature
- Industrial temperature information available upon request

BLOCK DIAGRAM



PIN ASSIGNMENT

V _{CC}	1	20	V _{CC}
XTALIN0	2	19	SEL1
XTALOUT0	3	18	SEL0
XTALIN1	4	17	V _{CC}
XTALOUT1	5	16	Q0
XTALIN2	6	15	nQ0
XTALOUT2	7	14	V _{CC}
XTALIN3	8	13	nc
XTALOUT3	9	12	nc
V _{EE}	10	11	V _{EE}

ICS85357-11

20-Lead TSSOP

4.40mm x 6.50mm x 0.92mm body package

G Package

Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 14, 17, 20	V _{CC}	Power		Positive supply pins.
2	XTALIN0	Input		Parallel resonant crystal input.
3	XTALOUT0	Input		Parallel resonant crystal input.
4	XTALIN1	Input		Parallel resonant crystal input.
5	XTALOUT1	Input		Parallel resonant crystal input.
6	XTALIN2	Input		Parallel resonant crystal input.
7	XTALOUT2	Input		Parallel resonant crystal input.
8	XTALIN3	Input		Parallel resonant crystal input.
9	XTALOUT3	Input		Parallel resonant crystal input.
10, 11	V _{EE}	Power		Negative supply pins.
12, 13	nc	Unused		No connect.
15, 16	nQ0, Q0	Output		Differential clock outputs. LVPECL interface levels.
18	SEL0	Input	Pulldown	Clock select input. LVCMOS / LVTTTL interface levels.
19	SEL1	Input	Pulldown	Clock select input. LVCMOS / LVTTTL interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		KΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		KΩ

TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs		Clock Out
SEL1	SEL0	CLK
0	0	XTALIN0, XTALOUT0
0	1	XTALIN1, XTALOUT1
1	0	XTALIN2, XTALOUT2
1	1	XTALIN3, XTALOUT3



ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to $V_{CC} + 0.5V$
Outputs, V_O	-0.5V to $V_{CC} + 0.5V$
Package Thermal Impedance, θ_{JA}	73.2°C/W (0 lfm)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Positive Supply Voltage		3.135	3.3	3.465	V
I_{EE}	Power Supply Current				50	mA

TABLE 4B. LVCMOS / LVTTTL DC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	SEL0, SEL1	2		$V_{CC} + 0.3$	V
V_{IL}	Input Low Voltage	SEL0, SEL1	-0.3		0.8	V
I_{IH}	Input High Current	SEL0, SEL1 $V_{CC} = V_{IN} = 3.465V$			150	μA
I_{IL}	Input Low Current	SEL0, SEL1 $V_{CC} = 3.465V, V_{IN} = 0V$	-5			μA

TABLE 4C. LVPECL DC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		$V_{CC} - 1.4$		$V_{CC} - 1.0$	V
V_{OL}	Output Low Voltage; NOTE 1		$V_{CC} - 2.0$		$V_{CC} - 1.7$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to $V_{CC} - 2V$.

TABLE 5. CRYSTAL CHARACTERISTICS

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation / cut		Fundamental / Parallel Resonant			
Frequency		10		27	MHz
Equivalent Series Resistance (ESR)				70	Ω
Shunt Capacitance				7	pF

TABLE 6. AC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = 0^\circ C$ TO $70^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency Range		10		27	MHz
t_R / t_F	Output Rise/Fall Time	20% to 80%	300		700	ps
odc	Output Duty Cycle; NOTE 1, 2		47		53	%
oscTOL	Crystal Oscillator Tolerance; NOTE 1			± 20		ppm

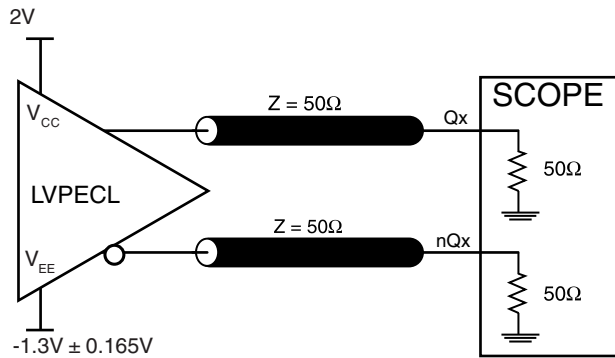
All parameters measured at 25MHz unless noted otherwise.

NOTE 1: Measured using C1 = 22pF and C2 = 27pF in parallel with 18pF crystals. Refer to Crystal Input Interface in the Application Section.

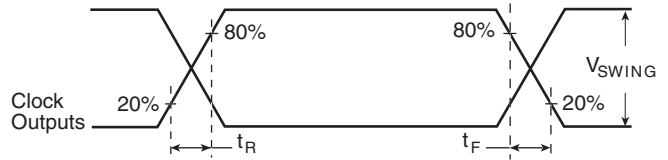
NOTE 2: This parameter is defined in accordance with JEDEC Standard 65.



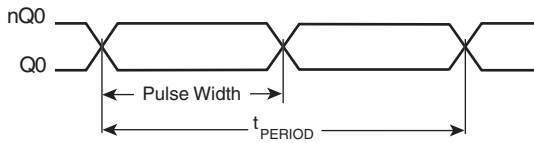
PARAMETER MEASUREMENT INFORMATION



3.3V OUTPUT LOAD AC TEST CIRCUIT



OUTPUT RISE/FALL TIME



$$\text{odc} = \frac{t_{\text{PW}}}{t_{\text{PERIOD}}}$$

OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD



APPLICATION INFORMATION

CRYSTAL INPUT INTERFACE

A crystal can be characterized for either series or parallel mode operation. The ICS85357-11 has a built-in crystal oscillator circuit. This interface can accept either a series or parallel crystal without additional components and generate frequencies with accuracy

suitable for most applications. Additional accuracy can be achieved by adding two small capacitors C1 and C2 as shown in *Figure 1*. Typical results using parallel 18pF crystals are shown in Table 7.

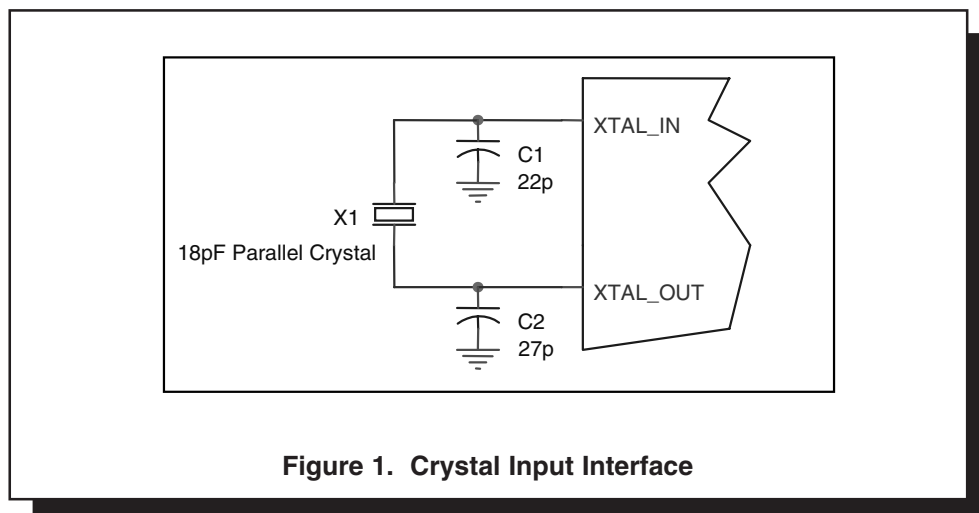


Table 7. TYPICAL RESULTS OF CRYSTAL INPUT INTERFACE FREQUENCY FINE TUNING

Crystal Frequency (MHz)	C1 (pF)	C2 (pF)	Measured Output Frequency (MHz)	Accuracy (PPM)	Duty Cycle (%)
14.31818	22	27	14.318011	-12	47.46
15.00	22	27	14.999862	-9	47.70
16.66	22	27	16.660162	10	47.70
19.44	22	27	19.440081	4	46.85
24.00	22	27	24.000183	8	46.00



TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 2A and 2B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

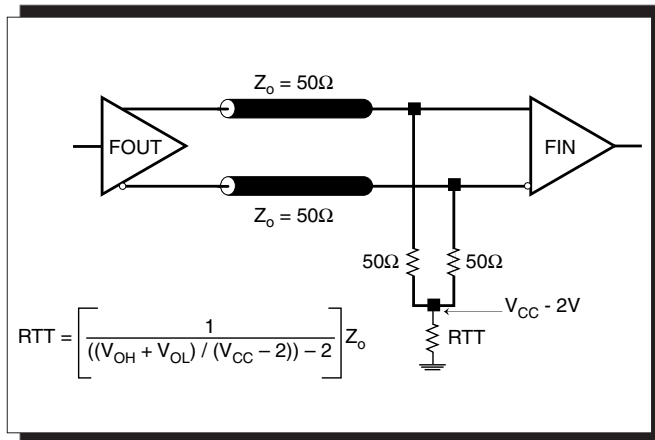


FIGURE 2A. LVPECL OUTPUT TERMINATION

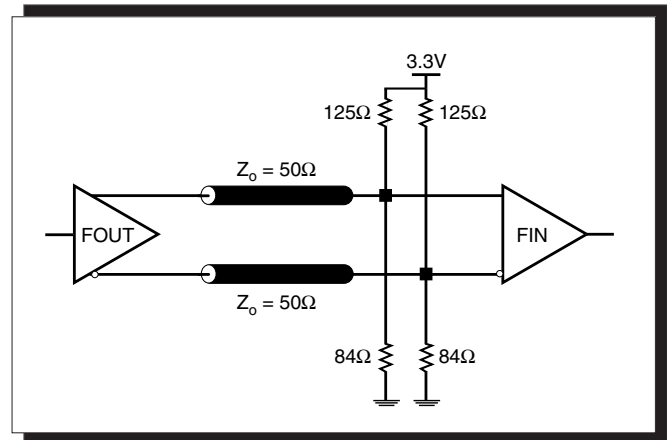


FIGURE 2B. LVPECL OUTPUT TERMINATION



POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS85357-11. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS85357-11 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{EE_MAX} = 3.465V * 50mA = 173.3mW$
- Power (outputs)_{MAX} = **30.2mW/Loaded Output pair**

$$\text{Total Power}_{MAX} (3.465V, \text{ with all outputs switching}) = 173.3mW + 30.2mW = \mathbf{203.5mW}$$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 66.6°C/W per Table 8 below.

Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ C + 0.204W * 66.6^\circ C/W = 83.6^\circ C. \text{ This is well below the limit of } 125^\circ C$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

TABLE 8. THERMAL RESISTANCE θ_{JA} FOR 20-PIN TSSOP, FORCED CONVECTION

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 3*.

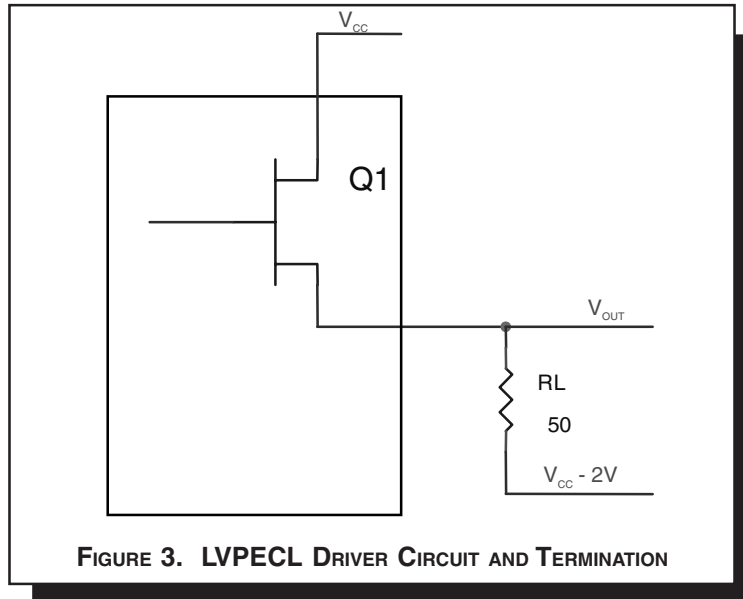


FIGURE 3. LVPECL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CC} - 2V$.

- For logic high, $V_{OUT} = V_{OH_MAX} = V_{CC_MAX} - 1.0V$

$$(V_{CC_MAX} - V_{OH_MAX}) = 1.0V$$

- For logic low, $V_{OUT} = V_{OL_MAX} = V_{CC_MAX} - 1.7V$

$$(V_{CC_MAX} - V_{OL_MAX}) = 1.7V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - (V_{CC_MAX} - V_{OH_MAX}))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - 1V)/50\Omega] * 1V = 20.0mW$$

$$Pd_L = [(V_{OL_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - (V_{CC_MAX} - V_{OL_MAX}))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd_H + Pd_L = 30.2mW



RELIABILITY INFORMATION

TABLE 9. θ_{JA} VS. AIR FLOW TABLE FOR 20 LEAD TSSOP

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS85357-11 is: 413



PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

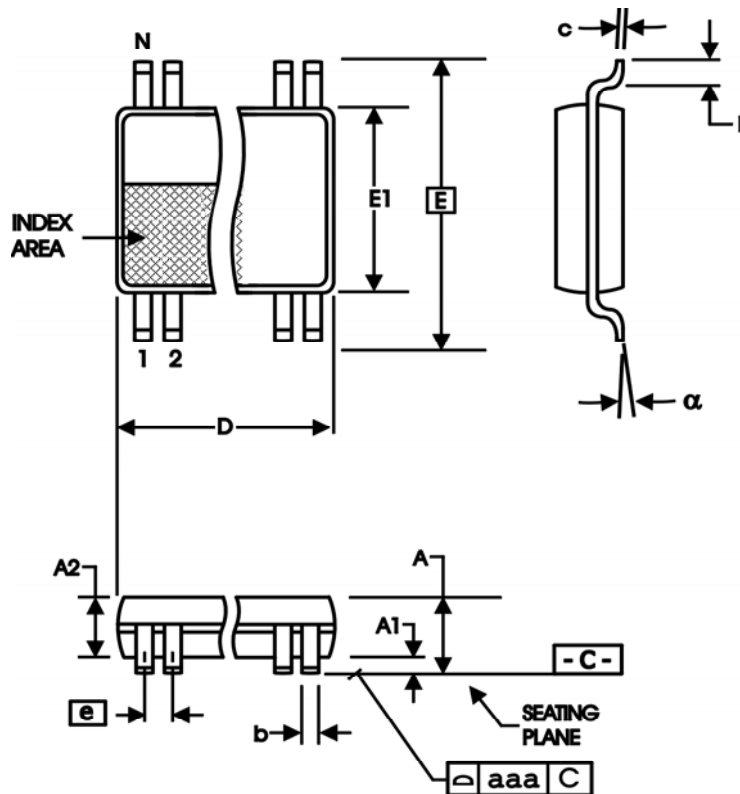


TABLE 10. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
alpha	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153



Integrated
Circuit
Systems, Inc.

ICS85357-11

4:1 OR 2:1, CRYSTAL OSCILLATOR-TO-3.3V LVPECL / ECL MULTIPLEXER

TABLE 11. ORDERING INFORMATION

Part/Order Number	Marking	Package	Count	Temperature
ICS85357AG-11	85357AG11	20 lead TSSOP	72 per tube	0°C to 70°C
ICS85357AG-11T	85357AG11	20 lead TSSOP on Tape and Reel	2500	0°C to 70°C

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REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change	Date	
A		8	Added Termination for LVPECL Outputs section.	5/30/02	
A		5	3.3V Output Load Test Circuit Diagram, corrected $V_{EE} = -1.3V \pm 0.135V$ to read $V_{EE} = -1.3V \pm 0.165V$.	8/26/02	
		6	Revised Output Rise/Fall Time Diagram.		
B	T4B	3	LVC MOS table - changed V_{IH} from 3.765 Max. to $V_{CC} + 0.3$ Max.	1/16/03	
	T4C	3	LVPECL table - changed V_{SWING} from 0.85V Max. to 1.0V Max.		
	T6	4	AC table - deleted t_{PD} , $t_{sk(pp)}$ and Notes 1 and 2. Updated format.		
C		1	Changed maximum crystal frequency from 25MHz to 27MHz. Changed Output Frequency bullet from 25MHz to 27MHz.	10/7/04	
		T2	2		Pin Characteristics Table - changed C_{IN} from 4pF max. to 4pF typical.
		T5	3		Crystal Characteristics Table - changed maximum Frequency from 25MHz to 27MHz.
		T6	3		AC Characteristics Table - changed maximum Output Frequency Range from 25MHz to 27MHz.